



# High Speed, Dual DPDT Analog Switch

## **Features**

→ CMOS Technology for Analog Applications

**→** Low On-Resistance:  $2.0\Omega$ 

Wide VCC Range: +1.65V to +4.3V

→ ICC Maximum  $1\mu A @ TA = +25$ °C

**→** Rail-to-Rail Switching Throughout Signal Range

**→** Fast Switching Speed: 10ns TYP. at 3.0V

**→** High Off Isolation: -67dB@1MHz

Crosstalk Rejection: -100dB@1MHz **→** 

→ Wide Bandwidth: 330MHz

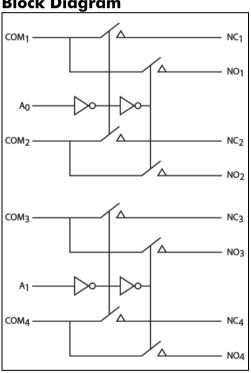
→ Interfaces with 1.8V Chipset

→ High ESD performance: 8kV for I/O to GND

**→** Extended Industrial Temperature Range: -40°C to 85°C

Packaging (Pb-free & Green): UQFN-16 1.8mmx2.6mm

**Block Diagram** 



## **Function Truth Table**

$A_0$	Function	$A_1$	Function
0	NC <sub>1, 2</sub> Connected to COM <sub>1, 2</sub>	0	NC <sub>3, 4</sub> Connected to COM <sub>3, 4</sub>
1	NO <sub>1, 2</sub> Connected to COM <sub>1, 2</sub>	1	NO <sub>3, 4</sub> Connected to COM <sub>3, 4</sub>

## **Description**

The PI3A3899 is a dual double-pole double-throw (DPDT) CMOS switch. It can be used as low power audio and dual SIM card applications. Specified over a wide operating power supply voltage range, +1.65V to +4.3V, the switch has a low On-Resistance of  $2.4\Omega$  at 3.0V.

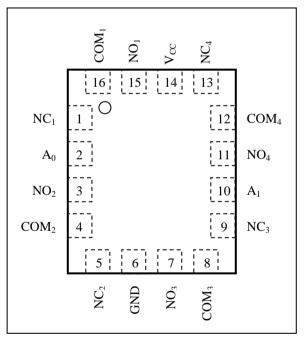
Control inputs, Ax, tolerate input drive signals up to 5V, independent of supply voltage.

## **Applications**

- Cell Phones
- **PDAs**
- Portable Instrumentation Battery Powered
- Computer Peripherals
- **Dual SIM Card Switching**

# **Pin Configuration**

UQFN16 1.8mmx2.6mm Package (Top View)

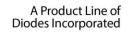


Pin Description

Pin#	Name	Description	
4, 8, 12, 16	$COM_X$	Common Output / Data Port	
1, 5, 9, 13	$NC_X$	Data Port (normally connect)	
3, 7, 11, 15	$NO_X$	Data Port (normally open)	
2, 10	$A_0, A_1$	Logic Input Control	
6	GND	Ground	
14	Vcc	Positive Power Supply	

**Notes**: X = 1, 2, 3, or 4







# **Maximum Ratings**

Storage Temperature	65°C to +150°C
Ambient Temperature	
ESD(HBM)	4kV for All Pins
	8kV for I/O to GND
Supply Voltage V <sub>CC</sub>	0.5V to +4.6V
Control Input Voltage (V <sub>INX</sub> )	0 to +5.0V
DC Input Voltage (V <sub>INPUT</sub> )	0.5V to +4.6V
Continuous Current NO/NC/COM	±400mA
Peak Current NO/NC/COM (Pulse at 1ms 10% duty cycle	e)±500mA

## Note:

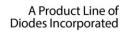
Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**Recommended Operating Conditions** 

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
$V_{CC}$	Supply Voltage	-	1.65	-	4.3	V
V <sub>INX</sub>	Control Input Voltage	-	0	-	4.3	V
$V_{INPUT}$	Switch Input Voltage	-	-0.3	-	$V_{CC}$	V
$T_A$	Operating Temperature	-	-40	25	85	°C
$t_r, t_f$	Input Rise and Fall Time	Control Input pins $V_{CC} = 2.3V$ to $3.6V$	0	-	10	ns/V

**Note**: Control input must be held HIGH or LOW; it must not float.







# **DC** Electrical Characteristics

 $(V_{CC}=1.65 \text{ to } 4.3 \text{V}, \text{GND=0V}, \text{V}_{IH}\text{=}+1.6 \text{V}, \text{V}_{IL}\text{=}+0.4 \text{V}, \text{T}_{A}=-40 ^{\circ}\text{C} \text{ to } 85 ^{\circ}\text{C}, \text{unless otherwise noted. Typical values are at 3V and }+25 ^{\circ}\text{C}.)$ 

Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Units		
Analog Signal Range	$egin{array}{c} V_{NO}, V_{NC}, \ V_{COM} \end{array}$	-		0	-	$V_{CC}$	V		
			V <sub>CC</sub> =	2.7V,	-	2.2	3.6		
On-Resistance	R <sub>ON</sub>	$I_{COM} = 100 \text{mA}, V_{NO} \text{ or}$	V <sub>CC</sub> =	3.0V,	-	2.0	3	Ω	
		$V_{NC} = 1V$ , Test Circuit 1	V <sub>CC</sub> =	4.3V	-	1.6	2.4		
On-Resistance Match		$I_{COM} = 100 \text{mA}, V_{NO} \text{ or}$	V <sub>CC</sub> =	3.0V	-	0.2	-		
Between Channels	$\Delta R_{ON}$	$V_{NC} = 1V$ , Test Circuit 1	V <sub>CC</sub> =	4.3V	-	0.2	-	Ω	
On-Resistance		$I_{COM} = 100 \text{mA}, V_{NO} \text{ or}$	V <sub>CC</sub> =	3.0V	-	0.6			
Flatness	$R_{ONF}$	$V_{NC} = 0 \sim V_{CC}$ , Test Circuit 1	V <sub>CC</sub> =	4.3V	-	0.5		Ω	
Source Off Leakage Current	I <sub>OFF (NO)</sub> or I <sub>OFF (NC)</sub>	$V_{CC}$ =4.3V, $V_{NO}$ or $V_{NC}$ = 4.0V/4.3V	4.3V/0V	$V_{\rm COM} =$	-	-	1	4	
Channel On Leakage Current	$I_{NC(ON)},$ $I_{NO(ON)},$ $I_{COM}$ $(ON)$	$V_{CC}$ =4.3V, $V_{NO}$ or $V_{NC}$ = 4.3V/0V, $V_{COM}$ = 0V/4.3V or floating			-	-	1	μΑ	
Input Logic High	V <sub>IH</sub>	$V_{CC} = 3.0V$		1.2	-	-			
Input Logic High	▼ IH	$V_{CC} = 4.3V$			1.3	-	-	V	
Input Logic Low	$V_{IL}$ $V_{CC} = 3.0 V$		-	-	0.5	<u> </u>			
	IL.	$V_{CC} = 4.3V$			-	-	0.6		
$ \begin{array}{ c c c c c }\hline IN \ Input \ Leakage \\ Current \\ \hline \end{array} \qquad \qquad I_{IN} \qquad \qquad V_{CC} = 4.3V, V_{CC} = 4$		$V_{CC} = 4.3V, V_{IN} = 0 \sim 4.3V$	$V, V_{IN} = 0 \sim 4.3 V$			-	+/-1	μΑ	
Turn-On Time	Furn-On Time $t_{ON}$ $R_L=50\Omega$ , $C_L=35$ pF, $T_A=25$ °C, See Test		e Test	-	8	-	ns		
Turn-Off Time t <sub>OFF</sub>		Circuit Figure 2			-	12	-	ns	
Break-Before-Make Delay	$t_{\rm D}$	T <sub>A</sub> =25°C, See Test Circuit Figure 3		-	9	-	ns		
NC-NO and COM- NC/NO Off-Isolation	O <sub>ISO</sub>	$V_{BIAS} = 1.5V, V_{IN} = 0 dBm,$ $T_A = 25$ °C, See Test Circuit Figure 4  1MHz		-	-67	-	dB		
Channel-to-Channel Crosstalk	X <sub>TALK</sub>	$V_{BIAS} = 1.5V, V_{IN} = 0 dBm,$ $T_A = 25$ °C, See Test Circuit Figure 5		_	-100	-	dB		
3dB Bandwidth	$f_{3dB}$	C <sub>L</sub> =5pF, See Test Circuit Figure 6		-	330	-	MHz		
Total Harmonic Distortion	THD	$V_{CC}$ =3.0V, f=20 Hz to 20 kHz, RL =32 $\Omega$ , $V_{IN}$ = 1.0 VPP		-	0.03	-	%		
Charge Injection Select Input to Common I/O	Q	$V_{IN} = GND$ , $R_S = 0$ , $C_L = 1nF$ , $T_A = 25$ °C, See Test Circuit Figure 7			-	13	-	pC	
Off Capacitance	C <sub>NC(OFF)</sub>	f=1MHz, TA=25°C, See Test Circuit Figure 8		-	7	-			
	$C_{NO(OFF)}$			-	7	-	pF		
On Capacitance C <sub>ON</sub> f=1MHz, TA=25 °C, See Test Circuit Figure		cuit Figure 9	-	15	-				
Power Supply Current $I_{CC}$ $V_{CC} = 4.3V, V_{IN} = 0V \text{ or } V_{CC}$				-	=-	1	μA		







# **Test Circuits and Timing Diagrams**

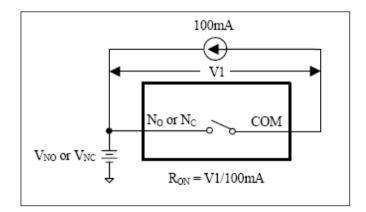


Figure 1. On Resistance

**Notes:** Unused input (NC or NO) must be grounded.

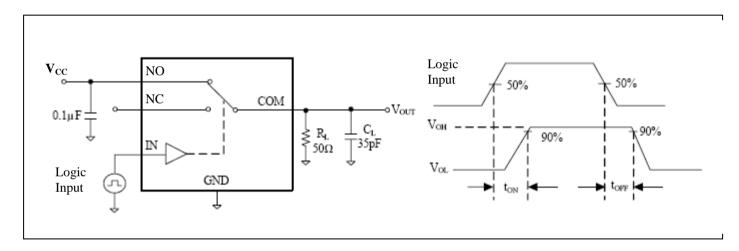


Figure 2. Switching Times

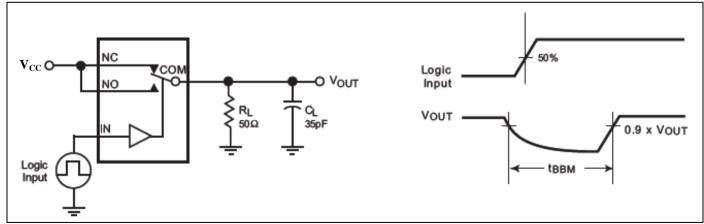
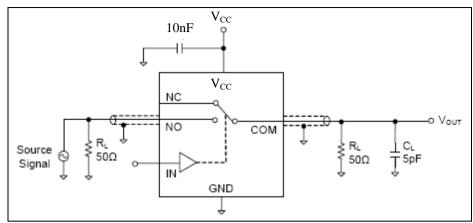


Figure 3. Break Before Make Interval Timing







**Figure 4. Off Isolation Test** 

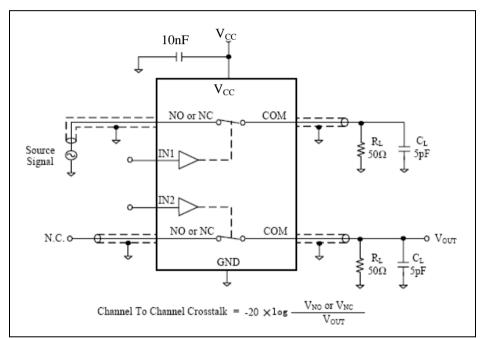


Figure 5. Channel-to-Channel Cross Talk

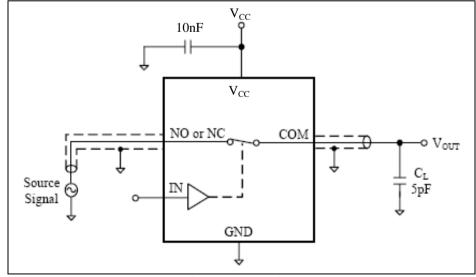


Figure 6. Bandwidth





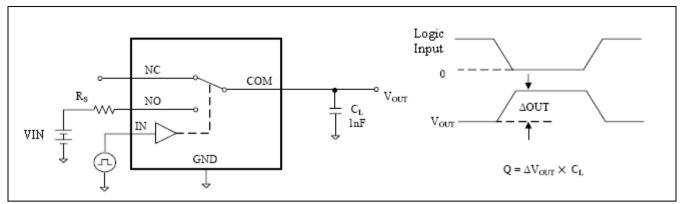
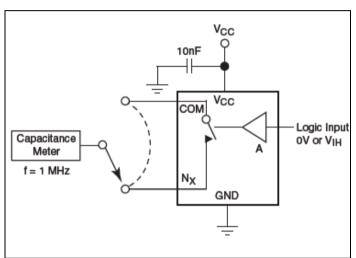


Figure 7. Charge Injection (Q)



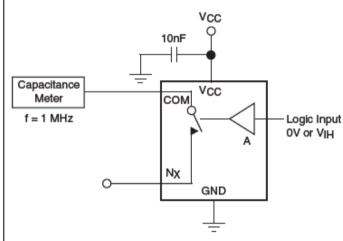


Figure 8. Channel Off Capacitance

Figure 9. Channel On Capacitance

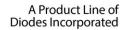
# **Part Marking**

ZT Package



YW: Year and Workweek

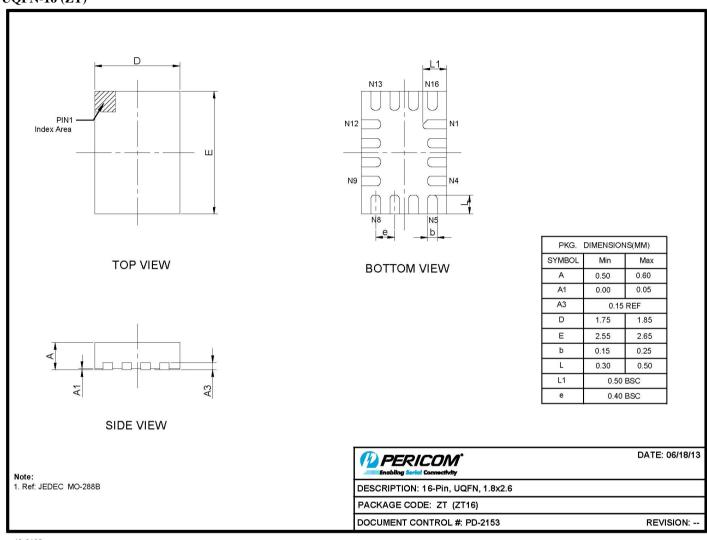






# **Package Mechanical**

**UQFN-16 (ZT)** 



13-0192

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# **Ordering Information**

Part Number	Package Code	Package Description
PI3A3899ZTEX	ZT	16-Pin, 1.8x2.6 (UQFN)

- EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
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